

256 Kbit (32K x8) SERIAL RTC

FEATURES SUMMARY

- 5V OPERATING VOLTAGE
- SERIAL INTERFACE SUPPORTS EXTENDED I²C BUS ADDRESSING (400 KHz)
- AUTOMATIC SWITCH-OVER and DESELECT CIRCUITRY
- POWER-FAIL DESELECT VOLTAGES:
 - M41T256Y: $V_{CC} = 4.5$ to $5.5V$;
 - $V_{PFD} = 4.2 < V_{PFD} < 4.5V$
- COUNTERS FOR TENTHS/HUNDREDTHS OF SECONDS, SECONDS, MINUTES, HOURS, DAY, DATE, MONTH, and YEAR
- PROGRAMMABLE SOFTWARE CLOCK CALIBRATION
- 32,752 BYTES OF GENERAL PURPOSE RAM
- MICROPROCESSOR POWER-ON RESET
- HOLDS MICROPROCESSOR IN RESET UNTIL SUPPLY VOLTAGE REACHES STABLE OPERATING LEVEL
- AUTOMATIC ADDRESS-INCREMENTING
- TAMPER INDICATION CIRCUIT with TIME-STAMP
- SLEEP MODE FUNCTION
- PACKAGING INCLUDES A 44-LEAD SOIC and SNAPHAT[®] TOP (to be ordered separately)
- SOIC PACKAGE PROVIDES DIRECT CONNECTION FOR A SNAPHAT[®] TOP WHICH CONTAINS THE BATTERY and CRYSTAL

Figure 1. 44-pin, Hatless SOIC Package

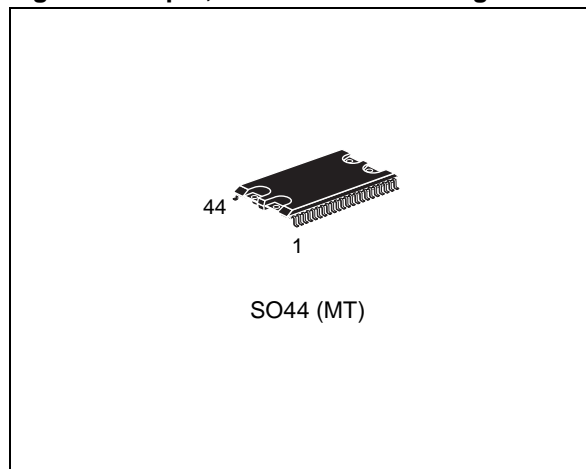


Figure 2. 44-pin SOIC Package

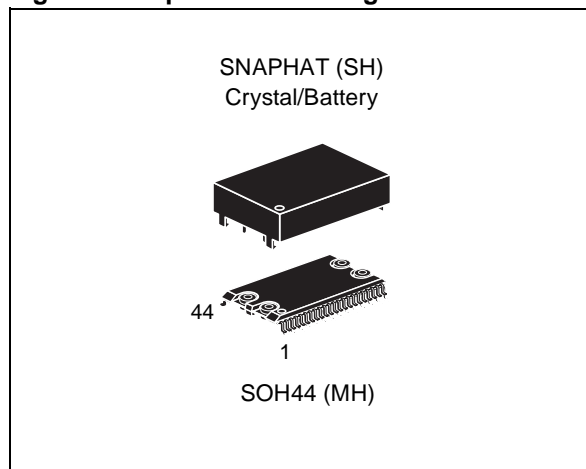


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SUMMARY DESCRIPTION

The M41T256Y Serial TIMEKEEPER® SRAM is a low power 256 Kbit static CMOS SRAM organized as 32K words by 8 bits. A built-in 32.768 kHz oscillator (external crystal controlled) and 8 bytes of the SRAM (see Figure 9, page 17) are used for the clock/calendar function and are configured in binary coded decimal (BCD) format.

Addresses and data are transferred serially via a two line, bi-directional I²C interface. The built-in address register is incremented automatically after each WRITE or READ data byte.

The M41T256Y has a built-in power sense circuit which detects power failures and automatically switches to the battery supply when a power failure occurs. The energy needed to sustain the SRAM and clock operations can be supplied by a lithium button-cell supply when a power failure occurs. Functions available to the user include a non-volatile, time-of-day clock/calendar, and Power-on Reset. The eight clock address locations contain the year, month, date, day, hour, minute, second, and tenths/hundredths of seconds in 24-hour BCD format. Corrections for 28, 29 (leap year - valid until year 2100), 30 and 31 day months are made automatically. The first clock address loca-

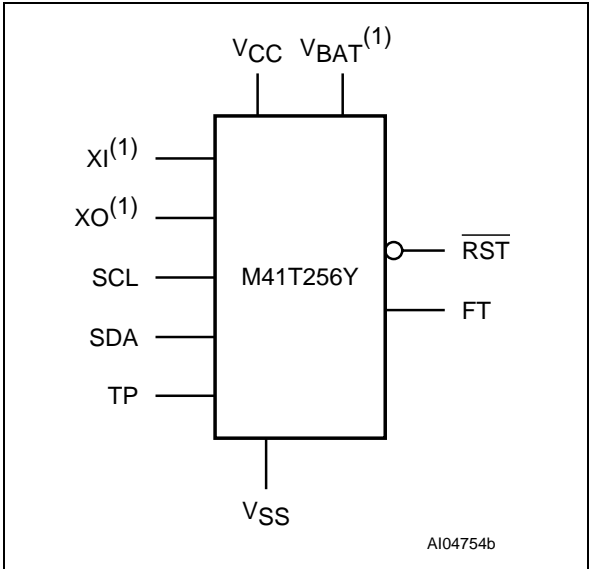
tion (7FF8h) stores the clock software calibration settings as well as the Write Clock Bit.

The M41T256Y is supplied in a 44-lead SOIC SNAPHAT® package (MH - which integrates both crystal and battery in a single SNAPHAT top) or a 44-pin “hatless” SOIC (MT). The 44-pin, 330mil SOIC provides sockets with gold-plated contacts at both ends for direct connection to a separate SNAPHAT housing containing the battery and crystal. The unique design allows the SNAPHAT battery/crystal package to be mounted on top of the SOIC package after the completion of the surface-mount process.

Insertion of the SNAPHAT housing after reflow prevents potential battery and crystal damage due to the high temperatures required for device surface-mounting. The SNAPHAT housing is also keyed to prevent reverse insertion. The 44-pin SOIC and crystal/battery packages are shipped separately in plastic, anti-static tubes or in Tape & Reel form. For the 44-lead SOIC, the battery/crystal package (e.g., SNAPHAT) part number is “M4Txx-BR12SH” (see Table 15, page 24).

Caution: Do not place the SNAPHAT battery/crystal top in conductive foam, as this will drain the lithium, button-cell battery.

Figure 3. Logic Diagram



Note: 1. For 44-pin SNAPHAT (MT) package only.

Table 1. Signal Names

XI ⁽¹⁾	Oscillator Input
XO ⁽¹⁾	Oscillator Output
FT	Frequency Test (Open drain)
$\overline{\text{RST}}$	Reset Output (Open drain)
SCL	Serial Clock Input
SDA	Serial Data Input/Output
V _{CC}	Supply Voltage
V _{BAT} ⁽¹⁾	Battery Supply Voltage
V _{SS}	Ground
TP	Tamper Input

Note: 1. For 44-pin SNAPHAT (MT) package only.

Figure 4. 44-pin SOIC Connections (MT)

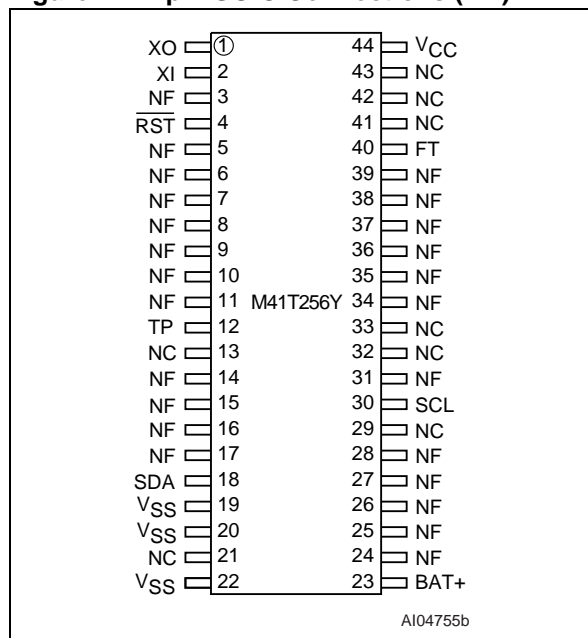
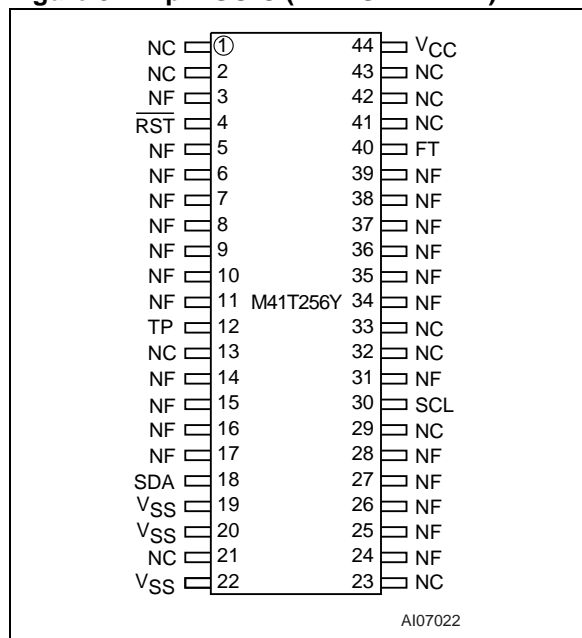
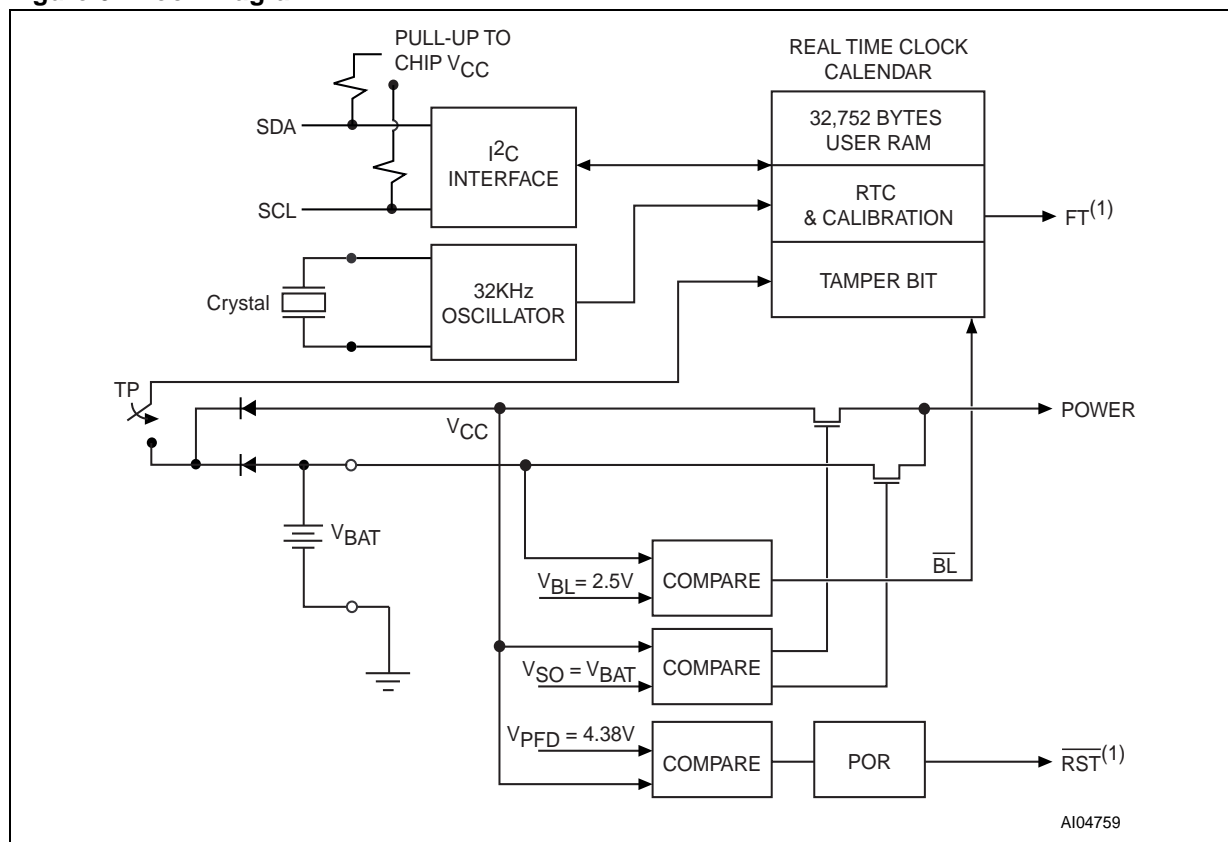


Figure 5. 44-pin SOIC (MH - SNAPHAT)



Note: No Function (NF) must be tied to VSS.

Figure 6. Block Diagram



Note: 1. Open drain output

MAXIMUM RATING

Stressing the device above the rating listed in the “Absolute Maximum Ratings” table may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is

not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

Table 2. Absolute Maximum Ratings

Symbol	Parameter		Value	Unit
T _{STG}	Storage Temperature (V _{CC} Off, Oscillator Off)	SNAPHAT®	–40 to 85	°C
		SOIC	–55 to 125	°C
T _{SLD} ⁽¹⁾	Lead Solder Temperature for 10 seconds		260	°C
V _{IO}	Input or Output Voltages		–0.3 to V _{CC} + 0.3	V
V _{CC}	Supply Voltage		–0.3 to 7.0	V
I _O	Output Current		20	mA
P _D	Power Dissipation		1	W

Note: 1. Reflow at peak temperature of 215°C to 225°C for < 60 seconds (total thermal budget not to exceed 180°C for between 90 to 120 seconds).

CAUTION: Negative undershoots below –0.3V are not allowed on any pin while in the Battery Back-up mode.

CAUTION: Do NOT wave solder SOIC to avoid damaging SNAPHAT sockets.

DC AND AC PARAMETERS

This section summarizes the operating and measurement conditions, as well as the DC and AC characteristics of the device. The parameters in the following DC and AC Characteristic tables are derived from tests performed under the Measure-

ment Conditions listed in the relevant tables. Designers should check that the operating conditions in their projects match the measurement conditions when using the quoted parameters.

Table 3. DC and AC Measurement Conditions

Parameter	M41T256Y
V _{CC} Supply Voltage	4.5 to 5.5V
Ambient Operating Temperature	–25 to 70°C
Load Capacitance (C _L)	100pF
Input Rise and Fall Times	≤ 50ns
Input Pulse Voltages	0.2V _{CC} to 0.8V _{CC}
Input and Output Timing Ref. Voltages	0.3V _{CC} to 0.7V _{CC}

Figure 7. AC Testing Input/Output Waveforms

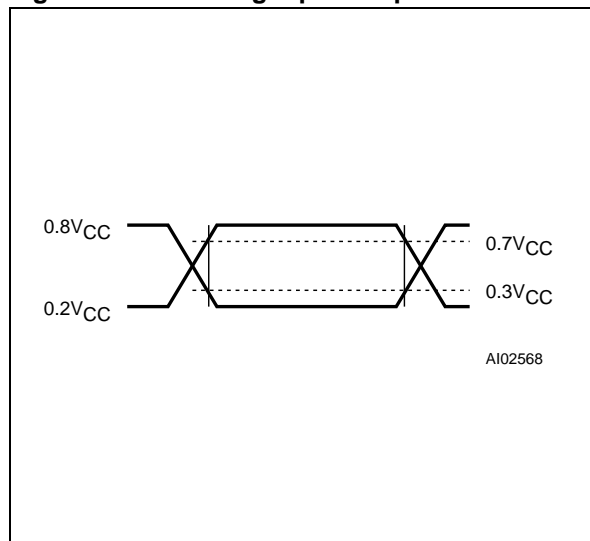


Table 4. Capacitance

Symbol	Parameter ^(1,2)	Min	Max	Unit
C _{IN}	Input Capacitance		7	pF
	Input Capacitance (Tamper Pin)		1000	pF
C _{IO} ⁽³⁾	Input / Output Capacitance		10	pF
t _{LP}	Low-pass filter input time constant (SDA and SCL)		50	ns

Note: 1. Effective capacitance measured with power supply at 5V; sampled only, not 100% tested.

2. At 25°C, f = 1MHz.

3. Outputs deselected.

Table 5. DC Characteristics

Sym	Parameter	Test Condition ⁽¹⁾	Min	Typ	Max	Unit
I _{BAT}	Battery Current OSC ON	T _A = 25°C, V _{CC} = 0V, V _{BAT} = 3.0V		1.5	1.9	μA
	Battery Current OSC OFF			1.0	1.4	μA
I _{CC1}	Supply Current	f = 400kHz		1.4	3.0	mA
I _{CC2}	Supply Current (Standby)	SCL, SDA = V _{CC} – 0.3V		1.0	2.5	mA
I _{LI}	Input Leakage Current	0V ≤ V _{IN} ≤ V _{CC}			±1	μA
I _{LO} ⁽²⁾	Output Leakage Current	0V ≤ V _{OUT} ≤ V _{CC}			±1	μA
V _{IH}	Input High Voltage		0.7V _{CC}		V _{CC} + 0.3	V
V _{IHB}	Input High Voltage in Battery Back-up for Tamper Pin		V _{BAT} – V _{diode}		V _{BAT}	V
V _{IL}	Input Low Voltage		–0.3		0.3V _{CC}	V
V _{BAT}	Battery Voltage		2.5		3.5	V
V _{OH}	Output High Voltage				V _{CC} + 0.3	V
V _{OL}	Output Low Voltage	I _{OL} = 3.0mA			0.4	V
	Output Low Voltage (Open Drain) ⁽³⁾	I _{OL} = 10mA			0.4	V
V _{PFD}	Power Fail Deselect		4.20		4.50	V
V _{SO}	Battery Back-up Switchover			V _{BAT}		V
R _{SW}	Switch Resistance on Tamper Pin				500	Ω

Note: 1. Valid for Ambient Operating Temperature: T_A = –25 to 70°C; V_{CC} = 4.5 to 5.5V (except where noted).

2. Outputs deselected.

3. For RST and FT pin (Open Drain).

Table 6. Crystal Electrical Characteristics (Externally Supplied)

Symbol	Parameter ^(1,2)	Typ	Min	Max	Unit
f ₀	Resonant Frequency	32.768			kHz
R _S	Series Resistance			35	kΩ
C _L	Load Capacitance	12.5			pF

Note: 1. STMicroelectronics recommends the KDS DT-38: 1TA/1TC252E127, Tuning Fork Type (thru-hole) or the DMX-26S: 1TJS125FH2A212, (SMD) quartz crystal for industrial temperature operations. KDS can be contacted at kouhou@kdsj.co.jp or <http://www.kdsj.co.jp> for further information on this crystal type.

2. Load capacitors are integrated within the M41T256Y. Circuit board layout considerations for the 32.768 kHz crystal of minimum trace lengths and isolation from RF generating signals should be taken into account.

OPERATING MODES

The M41T256Y clock operates as a slave device on the serial bus. Access is obtained by implementing a start condition followed by the correct slave address (D0h). The 256K bytes contained in the device can then be accessed sequentially in the following order:

0-7FEF = General Purpose RAM
 7FF0-7FF6 = Reserved
 7FF7h = Tenths/Hundredths Register
 7FF8h = Control Register
 7FF9h = Seconds Register
 7FFAh = Minutes Register
 7FFBh = Hour Register
 7FFCh = Tamper/Day Register
 7FFDh = Date Register
 7FFEh = Month Register
 7FFFh = Year Register

The M41T256Y clock continually monitors V_{CC} for an out-of tolerance condition. Should V_{CC} fall below V_{PFD} , the device terminates an access in progress and resets the device address counter. Inputs to the device will not be recognized at this time to prevent erroneous data from being written to the device from an out-of-tolerance system. When V_{CC} falls below V_{SO} , the device automatically switches over to the battery and powers down into an ultra low current mode of operation to conserve battery life. As system power returns and V_{CC} rises above V_{SO} , the battery is disconnected, and the power supply is switched to external V_{CC} . Write protection continues until V_{CC} reaches V_{PFD} plus t_{REC} .

For more information on Battery Storage Life refer to Application Note AN1012.

2-Wire Bus Characteristics

The bus is intended for communication between different ICs. It consists of two lines: a bi-directional data signal (SDA) and a clock signal (SCL). Both the SDA and SCL lines must be connected to a positive supply voltage via a pull-up resistor.

The following protocol has been defined:

- Data transfer may be initiated only when the bus is not busy.
- During data transfer, the data line must remain stable whenever the clock line is High.

- Changes in the data line, while the clock line is High, will be interpreted as control signals.

Accordingly, the following bus conditions have been defined:

Bus not busy. Both data and clock lines remain High.

Start data transfer. A change in the state of the data line, from High to Low, while the clock is High, defines the START condition.

Stop data transfer. A change in the state of the data line, from Low to High, while the clock is High, defines the STOP condition.

Data Valid. The state of the data line represents valid data when after a start condition, the data line is stable for the duration of the high period of the clock signal. The data on the line may be changed during the Low period of the clock signal. There is one clock pulse per bit of data.

Each data transfer is initiated with a start condition and terminated with a stop condition. The number of data bytes transferred between the start and stop conditions is not limited. The information is transmitted byte-wide and each receiver acknowledges with a ninth bit.

By definition a device that gives out a message is called "transmitter," the receiving device that gets the message is called "receiver." The device that controls the message is called "master." The devices that are controlled by the master are called "slaves."

Acknowledge. Each byte of eight bits is followed by one acknowledge clock pulse. This acknowledge clock pulse is a low level put on the bus by the receiver whereas the master generates an extra acknowledge related clock pulse. A slave receiver which is addressed is obliged to generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter.

The device that acknowledges has to pull down the SDA line during the acknowledge clock pulse in such a way that the SDA line is a stable Low during the High period of the acknowledge related clock pulse. Of course, setup and hold times must be taken into account. A master receiver must signal an end of data to the slave transmitter by not generating an acknowledge on the last byte that has been clocked out of the slave. In this case the transmitter must leave the data line High to enable the master to generate the STOP condition.

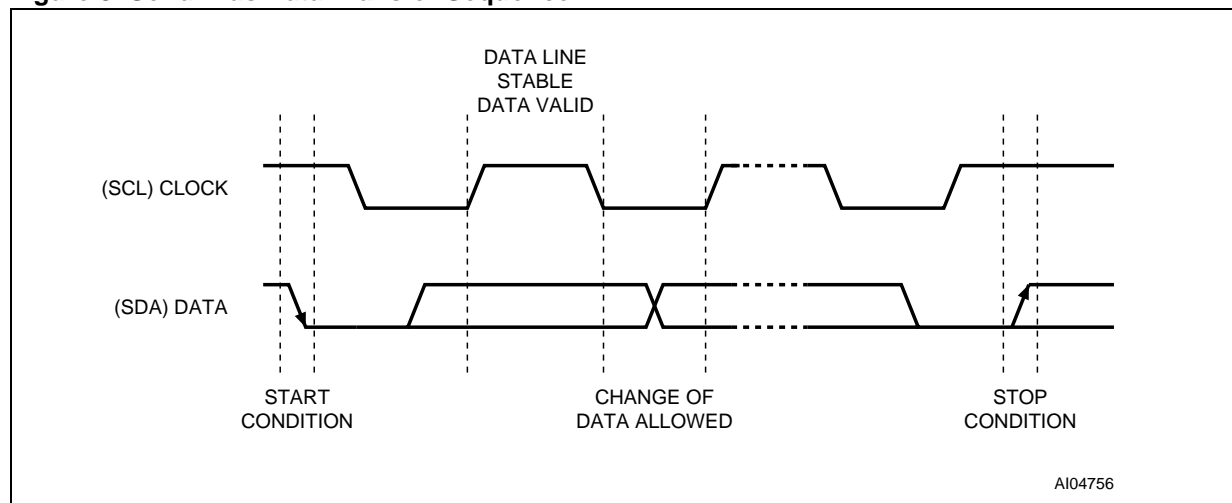
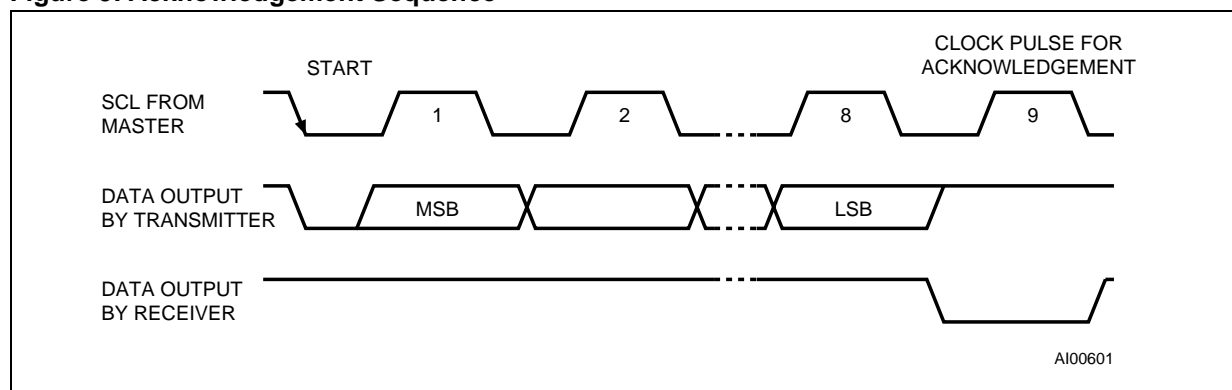
Figure 8. Serial Bus Data Transfer Sequence**Figure 9. Acknowledgement Sequence**

Figure 10. Bus Timing Requirements Sequence

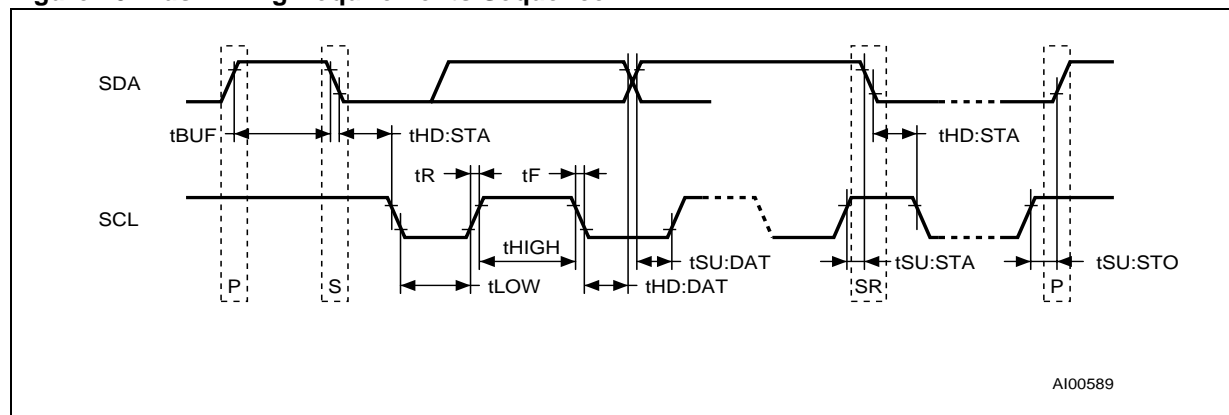


Table 7. AC Characteristics

Symbol	Parameter ⁽¹⁾	Min	Max	Unit
f_{SCL}	SCL Clock Frequency	0	400	kHz
t_{BUF}	Time the bus must be free before a new transmission can start	1.3		μs
t_F	SDA and SCL Fall Time		300	ns
$t_{HD:DAT}$	Data Hold Time	0		μs
$t_{HD:STA}$	START Condition Hold Time (after this period the first clock pulse is generated)	600		ns
t_{HIGH}	Clock High Period	600		ns
t_{LOW}	Clock Low Period	1.3		μs
t_R	SDA and SCL Rise Time		300	ns
$t_{SU:DAT}^{(2)}$	Data Setup Time	100		ns
$t_{SU:STA}$	START Condition Setup Time (only relevant for a repeated start condition)	600		ns
$t_{SU:STO}$	STOP Condition Setup Time	600		ns

Note: 1. Valid for Ambient Operating Temperature: $T_A = -25$ to $70^\circ C$; $V_{CC} = 4.5$ to $5.5V$ (except where noted).

2. Transmitter must internally provide a hold time to bridge the undefined region (300ns max) of the falling edge of SCL.

READ Mode

In this mode the master reads the M41T256Y slave after setting the slave address (see Figure 11, page 12). Following the WRITE Mode Control Bit ($R/W=0$) and the Acknowledge Bit, the byte addresses $A(0)$ and $A(1)$ are written to the on-chip address pointer (MSB of address byte $A(0)$ is a "Don't care"). Next the START condition and slave address are repeated followed by the READ Mode Control Bit ($R/W=1$). At this point the master transmitter becomes the master receiver. The data byte which was addressed will be transmitted and the master receiver will send an acknowledge bit to the slave transmitter. The address pointer is only incremented on reception of an Acknowledge Clock. The M41T256Y slave transmitter will now place the data byte at address $An+1$ on the bus, the master receiver reads and acknowledges the new byte and the address pointer is incremented to $An+2$.

This cycle of reading consecutive addresses will continue until the master receiver sends a STOP condition to the slave transmitter (see Figure 12, page 13).

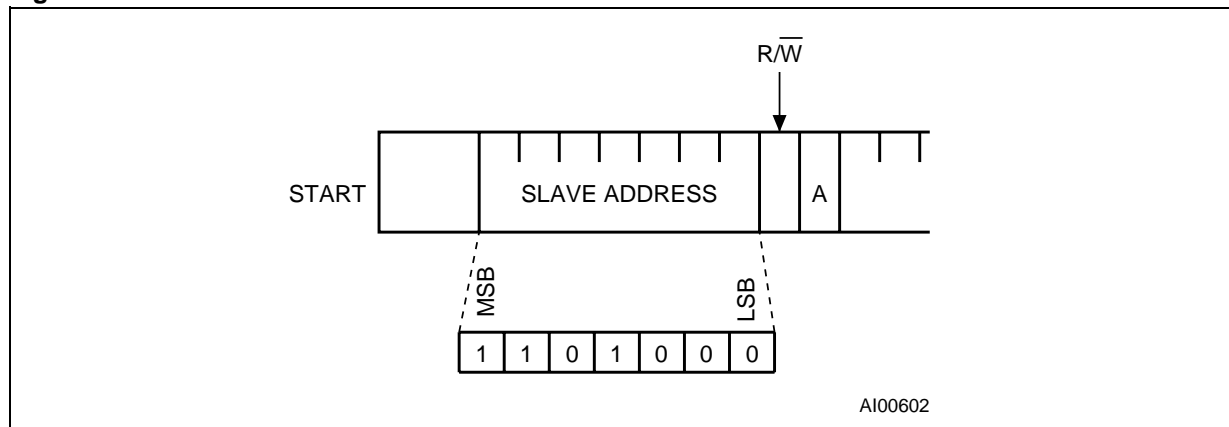
Note: Address pointer will wrap around from maximum address to minimum address if consecutive READ or WRITE cycles are performed.

An alternate READ Mode may also be implemented whereby the master reads the M41T256Y slave without first writing to the (volatile) address pointer. The first address that is read is the last one stored in the pointer (see Figure 13, page 13).

WRITE Mode

In this mode the master transmitter transmits to the M41T256Y slave receiver. Bus protocol is shown in Figure Figure 14, page 13. Following the START condition and slave address, a logic '0' ($R/W=0$) is placed on the bus and indicates to the addressed device that byte addresses $A(0)$ and $A(1)$ will follow and is to be written to the on-chip address pointer (MSB of address byte $A(0)$ is a "Don't care"). The data byte to be written to the memory is strobed in next and the internal address pointer is incremented to the next memory location within the RAM on the reception of an acknowledge bit. The M41T256Y slave receiver will send an acknowledge bit to the master transmitter after it has received the slave address (see Figure 11, page 12) and again after it has received each address byte.

Figure 11. Slave Address Location



Note: The most significant bit is sent first.

Figure 12. READ Mode Sequence

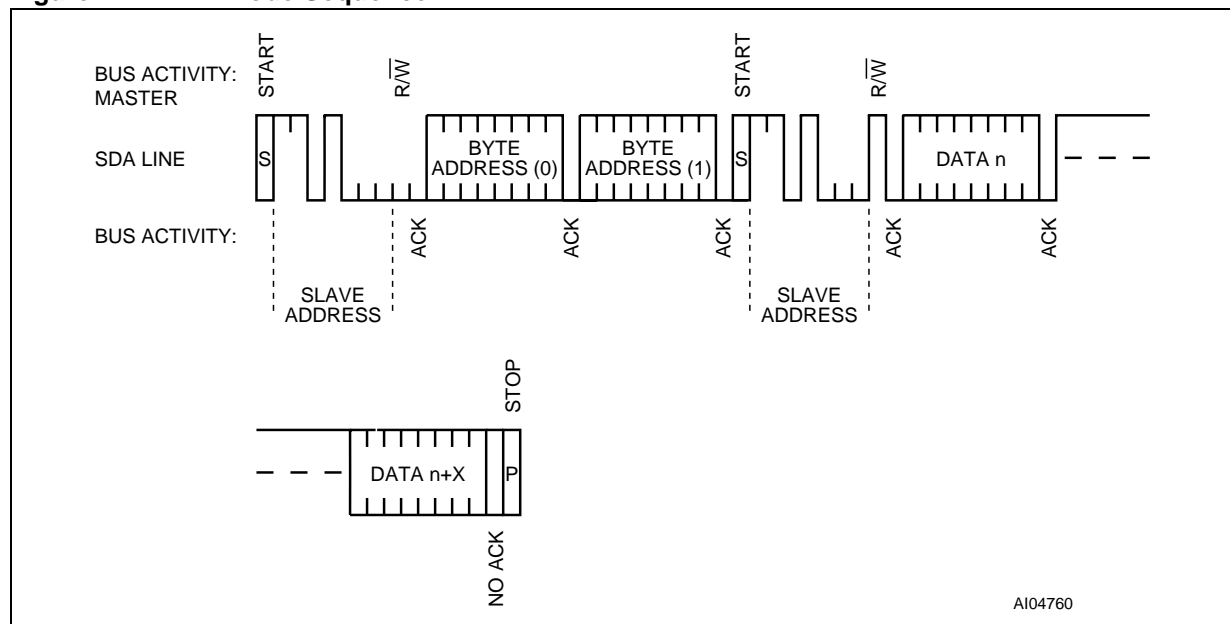


Figure 13. Alternate READ Mode Sequence

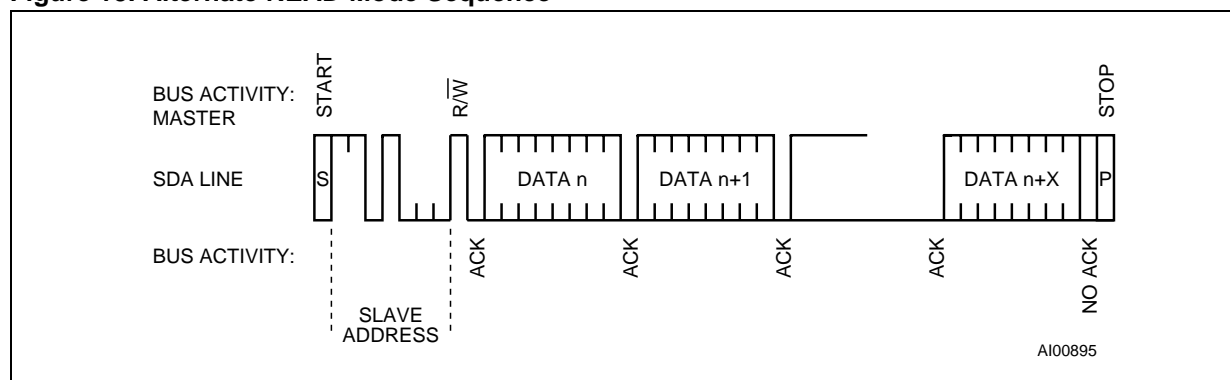
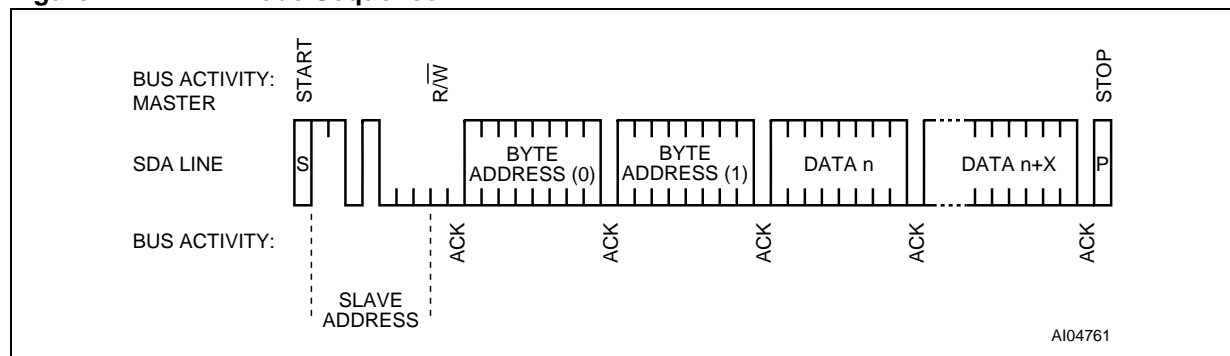


Figure 14. WRITE Mode Sequence



Data Retention Mode

With valid V_{CC} applied, the M41T256Y can be accessed as described above with READ or WRITE Cycles. Should the supply voltage decay, the M41T256Y will automatically deselect, write protecting itself when V_{CC} falls between V_{PFD} (max) and V_{PFD} (min). This is accomplished by internally inhibiting access to the clock registers. At this time, the Reset pin (RST) is driven active and will remain active until V_{CC} returns to nominal levels. When V_{CC} falls below the Battery Back-up Switchover Voltage (V_{SO}), power input is switched from the V_{CC} pin to the external battery and the clock registers and SRAM are maintained from the attached battery supply.

All outputs become high impedance. On power up, when V_{CC} returns to a nominal value, write protection continues for t_{REC} . The RST signal also remains active during this time (see Figure 15, page 15).

For a further more detailed review of lifetime calculations, please see Application Note AN1012.

Sleep Mode

In order to minimize the battery current draw while in storage, the M41T256Y provides the user with a battery "Sleep Mode," which disconnects the RAM memory array from the external Lithium battery normally used to provide non-volatile operation in the absence of V_{CC} . This can significantly extend the lifetime of the battery, when non-volatile operation is not needed.

Note: The Sleep Mode will remove power from the RAM array only and not affect the data retention of the TIMEKEEPER Registers (7FF0h through 7FFFh - this includes the Calibration Register).

The Sleep Mode (SLP) Bit located in register 7FF8h (D6), must be set to a '1' by the user while the device is powered by V_{CC} . This will "arm" the Sleep Mode latch, but not actually disconnect the RAM array from power until the next power-down cycle. This protects the user from immediate data loss in the event he inadvertently sets the SLP Bit. Once V_{CC} falls below V_{SO} (V_{BAT}), the Sleep Mode circuit will be engaged and the RAM array will be isolated from the battery, resulting in both a lower battery current, and a loss of RAM data.

Note: Upon initial battery attach or initial power application without the battery, the state of the SLP Bit will be undetermined. Therefore, the SLP Bit should be initialized to '0' by the user.

Additional current reduction can be achieved by setting the STOP (ST) Bit in register 7FF9h (D7), turning off the clock oscillator. This combination will result in the longest possible battery life, but also loss of time and data. When the device is again powered-up, the user should first read the SLP Bit to determine if the device is currently in Sleep Mode, then reset the bit to '0' in order to disable the Sleep Mode (this will NOT be automatically taken care of during the power-up).

Note: See AN1570, "M41T256Y Sleep Mode Function" for more information on Sleep Mode and battery lifetimes.

Figure 15. Power Down/Up Mode AC Waveforms

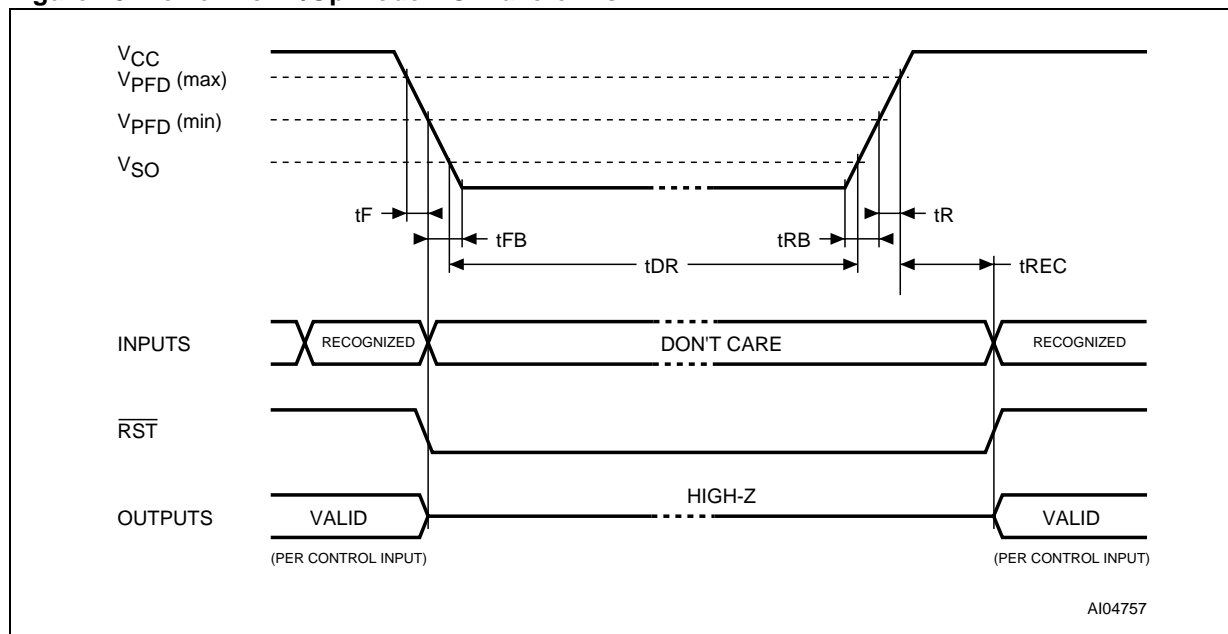


Table 8. Power Down/Up AC Characteristics

Symbol	Parameter ⁽¹⁾	Min	Typ	Max	Unit
$t_F^{(2)}$	$V_{PFD}(\text{max})$ to $V_{PFD}(\text{min})$ V_{CC} Fall Time	300			μs
$t_{FB}^{(3)}$	$V_{PFD}(\text{min})$ to V_{SS} V_{CC} Fall Time	10			μs
t_R	$V_{PFD}(\text{min})$ to $V_{PFD}(\text{max})$ V_{CC} Rise Time	10			μs
t_{RB}	V_{SS} to $V_{PFD}(\text{min})$ V_{CC} Rise Time	1			μs
t_{REC}	Power up Deselect Time	40		200	ms
t_{DR}	Expected Data Retention Time (OSC On, Sleep Mode Off)	$15^{(4)}$			YEARS

Note: 1. Valid for Ambient Operating Temperature: $T_A = -25$ to 70°C ; $V_{CC} = 4.5$ to 5.5V (except where noted).

2. $V_{PFD}(\text{max})$ to $V_{PFD}(\text{min})$ fall time of less than t_F may result in deselection/write protection not occurring until $200\mu\text{s}$ after V_{CC} passes $V_{PFD}(\text{min})$.

3. $V_{PFD}(\text{min})$ to V_{SS} fall time of less than t_{FB} may cause corruption of RAM data.

4. At 25°C and $V_{CC} = 0\text{V}$, using a BR2330 Li Battery. This drops to 7.2 years when using the M4T32-BR12SH with the oscillator running.

CLOCK OPERATION

Year, Month, and Date are contained in the last three registers of the TIMEKEEPER® Register Map (see Table 9). Bits D0 through D2 of the next register contain the Day (day of week). Finally, there are the registers containing the Seconds, Minutes, and Hours, respectively. The first clock register is the Control Register (this is described in the Clock Calibration section).

The nine Clock Registers may be read one byte at a time, or in a sequential block. The Control Register (Address location 7FF8h) may be accessed independently. Provision has been made to assure that a clock update does not occur while any of the nine clock addresses are being read. If a clock address is being read, an update of the clock registers will be halted. This will prevent a transition of data during the read.

Reading the Clock

The nine byte clock register (see Table 9) is used to both set the clock and to read the date and time from the clock, in a binary coded decimal format. The system-to-user transfer of clock data will be halted whenever the address being read is a clock address (7FF9h to 7FFFh). The update will resume either due to a Stop Condition or when the pointer increments to a RAM address.

This prevents reading data in transition. The TIMEKEEPER® cells in the Register Map are only data registers and not actual clock counters, so

updating the registers can be halted without disturbing the clock itself.

Setting the Clock

Bit D7 of the Control Register (7FF8h) is the Write Clock Bit. Setting the Write Clock Bit to a '1' will allow the user to write the desired Day, Date, and Time data in 24-hour BCD format. Resetting the Write Clock Bit to a '0' then transfers the values of all time registers (7FF8h-7FFFh) to the actual clock counters and resets the internal divider (or clock) chain.

Note: The Tenths/Hundredths of Seconds Register will automatically be reset to zero when the WRITE Clock Bit is set.

Other register bits such as FT, TEB, and ST may be written without setting the WC Bit. In such cases, the clock data will be undisturbed and will retain their previous values.

Stopping and Starting the Oscillator

The oscillator may be stopped at any time. If the device is going to spend a significant amount of time on the shelf, the oscillator can be turned off to minimize current drain on the battery. The Stop Bit (ST) is the most significant bit of the Seconds Register. Setting it to '1' stops the oscillator. Setting it to '0' restarts the oscillator in approximately one second.

Table 9. TIMEKEEPER® Register Map

Address	Data								Function/Range BCD Format	
	D7	D6	D5	D4	D3	D2	D1	D0		
7FFFh	10 Years				Year				Year	00-99
7FFEh	0	0	0	10M	Month				Month	01-12
7FFDh	0	0	10 Date		Date: Day of Month				Date	01-31
7FFCh	BL	FT	TEB	TB	0	Day of Week			Tamper/Day	0-1/01-07
7FFBh	0	0	10 Hours		Hours (24 Hour Format)				Hours	00-23
7FFAh	0	10 Minutes			Minutes				Minutes	00-59
7FF9h	ST	10 Seconds			Seconds				Seconds	00-59
7FF8h	WC	SLP	S	Calibration					Control	
7FF7h	0.1 Seconds				0.01 Seconds				Seconds	00-99
7FF6h	X	X	X	X	X	X	X	X	Reserved	
7FF5h	X	X	X	X	X	X	X	X	Reserved	
7FF4h	X	X	X	X	X	X	X	X	Reserved	
7FF3h	X	X	X	X	X	X	X	X	Reserved	
7FF2h	X	X	X	X	X	X	X	X	Reserved	
7FF1h	X	X	X	X	X	X	X	X	Reserved	
7FF0h	X	X	X	X	X	X	X	X	Reserved	

Keys: S = Sign Bit

FT = Frequency Test Bit

ST = Stop Bit

WC = Write Clock Bit

X = '1' or '0'

BL = Battery Low Flag (Read only bit)

TB = Tamper Bit (Read only bit)

TEB = Tamper Enable Bit

0 = Must be set to '0'

SLP = Sleep Mode Bit

Note: 7FF0h through 7FF6h are invalid addresses and when read will return arbitrary data.

Power-on Reset

The M41T256Y continuously monitors V_{CC} . When V_{CC} falls to the power fail detect trip point, the RST pulls low (open drain) and remains low on power-up for t_{REC} after V_{CC} passes V_{PFD} (max). The RST pin is an open drain output and an appropriate pull-up resistor should be chosen to control rise time.

Tamper Indication Circuit

The M41T256Y provides an independent input pin, the Tamper Pin (TP) which can be used to monitor a signal which can result in the setting of the Tamper Bit (TB) if the Tamper Enable Bit (TEB) is set to a '1.'

The Tamper Pin is triggered by being connected to V_{CC}/V_{BAT} through an external switch. This switch is normally open in the application, allowing the pin to be "floating" (internally latched to V_{SS} when TEB is set). When this switch is closed (connecting the pin to V_{CC}/V_{BAT}), the Tamper Bit will be immediately set. This allows the user to determine if the device has been physically moved or tampered with. The Tamper Bit is a "read only" bit and is reset only by taking the Tamper Pin to ground and resetting the Tamper Enable Bit to '0.'

This function operates both under normal power, and in battery back-up. If the switch closes during a power-down condition, the bit will still be set correctly.

Note: Upon initial battery attach or initial power application without the battery, the state of TEB (and TB) will be undetermined. Therefore TEB must be initialized to a '0.'

Tamper Event Time-Stamp

If a tamper occurs, not only will the Tamper Bit be set, but the event will also automatically be time-stamped. This is accomplished by freezing the normal update of the clock registers (7FF7h through 7FFFh) immediately following a tamper event. Thus, when tampering occurs, the user may first read the time registers to determine exactly when the tamper event occurred, then re-enable the clock update to the current time (and reset the Tamper Bit, TB) by resetting the Tamper Enable Bit (TEB).

The time update will then resume, and after either a Stop Condition or incrementing the address

pointer to a RAM address and back, the clock can be read to determine the current time.

Note: The Tamper Bit (TB) must always be set to '0' in order to read the current time.

Calibrating the Clock

The M41T256Y is driven by a quartz controlled oscillator with a nominal frequency of 32,768 Hz. The devices are tested not exceed ± 35 PPM (parts per million) oscillator frequency error at 25°C, which equates to about ± 1.53 minutes per month. When the Calibration circuit is properly employed, accuracy improves to better than $\pm 1/2$ PPM at 25°C.

The oscillation rate of crystals changes with temperature (see Figure 16, page 20). Therefore, the M41T256Y design employs periodic counter correction. The calibration circuit adds or subtracts counts from the oscillator divider circuit at the divide by 256 stage, as shown in Figure 17, page 20. The number of times pulses which are blanked (subtracted, negative calibration) or split (added, positive calibration) depends upon the value loaded into the five Calibration bits found in the Control Register. Adding counts speeds the clock up, subtracting counts slows the clock down.

The Calibration bits occupy the five lower order bits (D4-D0) in the Control Register (7FF8h). These bits can be set to represent any value between 0 and 31 in binary form. Bit D5 is a Sign Bit; '1' indicates positive calibration, '0' indicates negative calibration. Calibration occurs within a 64 minute cycle. The first 62 minutes in the cycle may, once per minute, have one second either shortened by 128 or lengthened by 256 oscillator cycles. If a binary '1' is loaded into the register, only the first 2 minutes in the 64 minute cycle will be modified; if a binary 6 is loaded, the first 12 will be affected, and so on.

Therefore, each calibration step has the effect of adding 512 or subtracting 256 oscillator cycles for every 125,829,120 actual oscillator cycles, that is $+4.068$ or -2.034 PPM of adjustment per calibration step in the calibration register. Assuming that the oscillator is running at exactly 32,768 Hz, each of the 31 increments in the Calibration byte would represent $+10.7$ or -5.35 seconds per month which corresponds to a total range of $+5.5$ or -2.75 minutes per month.

Two methods are available for ascertaining how much calibration a given M41T256Y may require.

The first involves setting the clock, letting it run for a month and comparing it to a known accurate reference and recording deviation over a fixed period of time. Calibration values, including the number of seconds lost or gained in a given period, can be found in Application Note AN934: TIMEKEEPER CALIBRATION. This allows the designer to give the end user the ability to calibrate the clock as the environment requires, even if the final product is packaged in a non-user serviceable enclosure. The designer could provide a simple utility that accesses the Calibration byte.

The second approach is better suited to a manufacturing environment, and involves the use of the FT pin. The pin will toggle at 512Hz, when the Stop Bit (ST) is '0,' and the Frequency Test Bit (FT) is '1.'

Any deviation from 512 Hz indicates the degree and direction of oscillator frequency shift at the test temperature. For example, a reading of 512.010124 Hz would indicate a +20 PPM oscillator frequency error, requiring a -10 (XX001010) to be loaded into the Calibration Byte for correction. Note that setting or changing the Calibration Byte does not affect the Frequency Test output frequency.

The FT pin is an open drain output which requires a pull-up resistor to V_{CC} for proper operation. A 500 to 10k resistor is recommended in order to

control the rise time. The FT Bit is cleared on power-down.

Battery Low Warning

The M41T256Y automatically performs battery voltage monitoring upon power-up. The Battery Low (BL) Bit, Bit D7 of Day Register, will be asserted if the battery voltage is found to be less than approximately 2.5V. The BL Bit will remain asserted until completion of battery replacement and subsequent battery low monitoring tests, during the next power-up sequence.

If a battery low is generated during a power-up sequence, this indicates that the battery is below approximately 2.5 volts and may not be able to maintain data integrity in the SRAM. Data should be considered suspect and verified as correct. A fresh battery should be installed. The battery may be replaced while V_{CC} is applied to the device.

The M41T256Y only monitors the battery when a nominal V_{CC} is applied to the device. Thus applications which require extensive durations in the battery back-up mode should be powered-up periodically (at least once every few months) in order for this technique to be beneficial. Additionally, if a battery low is indicated, data integrity should be verified upon power-up via a checksum or other technique.

Preferred Power-on/Battery Attach Defaults

See Table 10, below.

Table 10. Preferred Default Values

Condition	WC	TEB ⁽¹⁾	TB ⁽¹⁾	FT	ST ⁽¹⁾	SLP ⁽¹⁾
Battery Attach or Initial Power-up	0	X	X	0	X	X
Power-Cycling (with battery)	0	UC	UC	0	UC	UC

Note: 1. X = Undetermined; UC = Unchanged

Figure 16. Crystal Accuracy Across Temperature

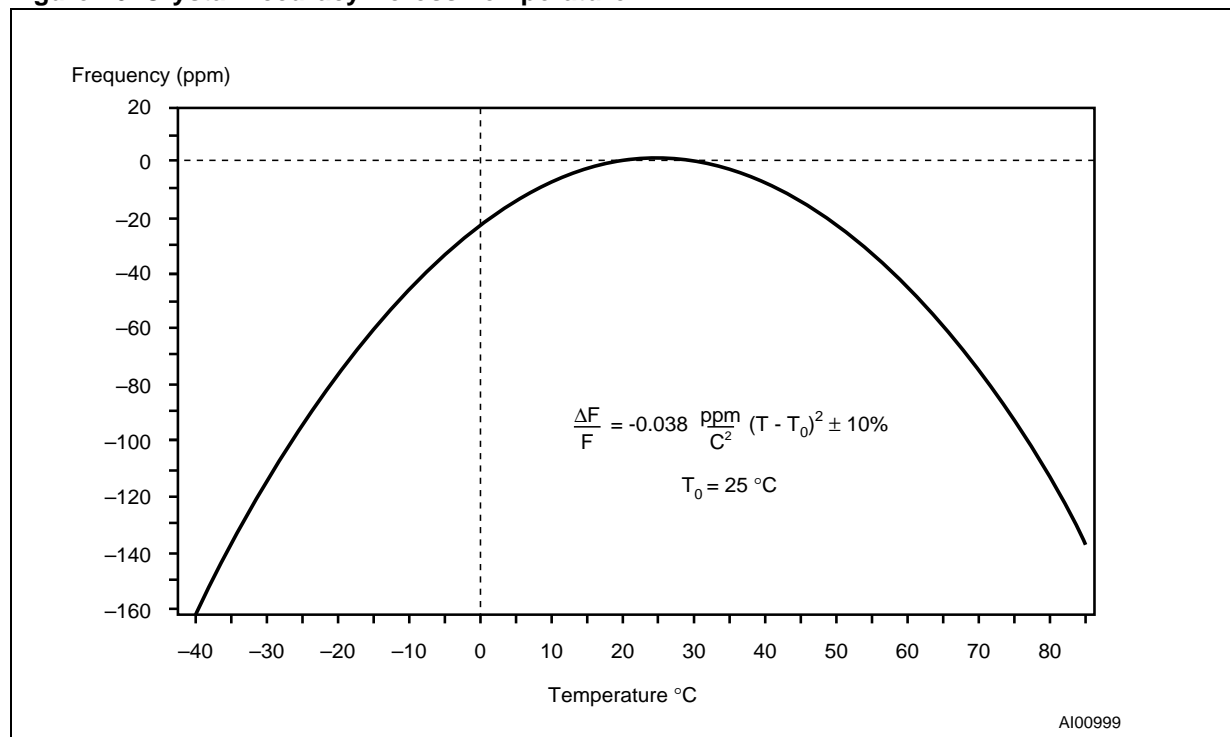
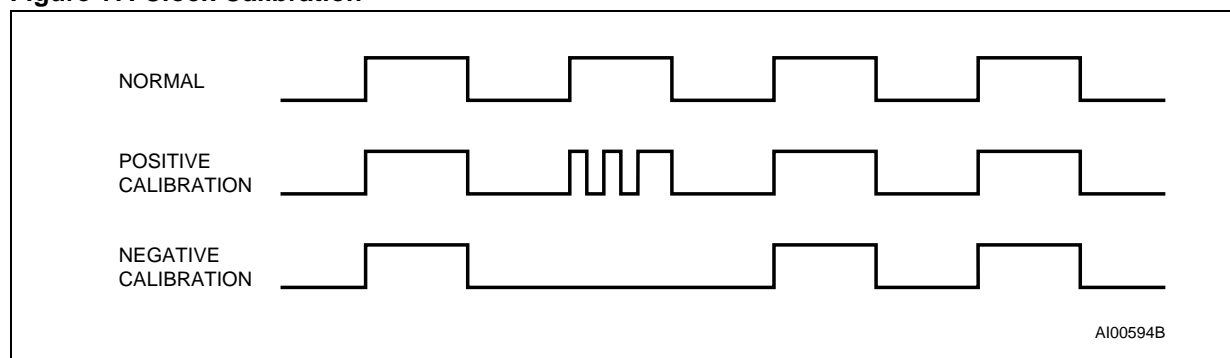
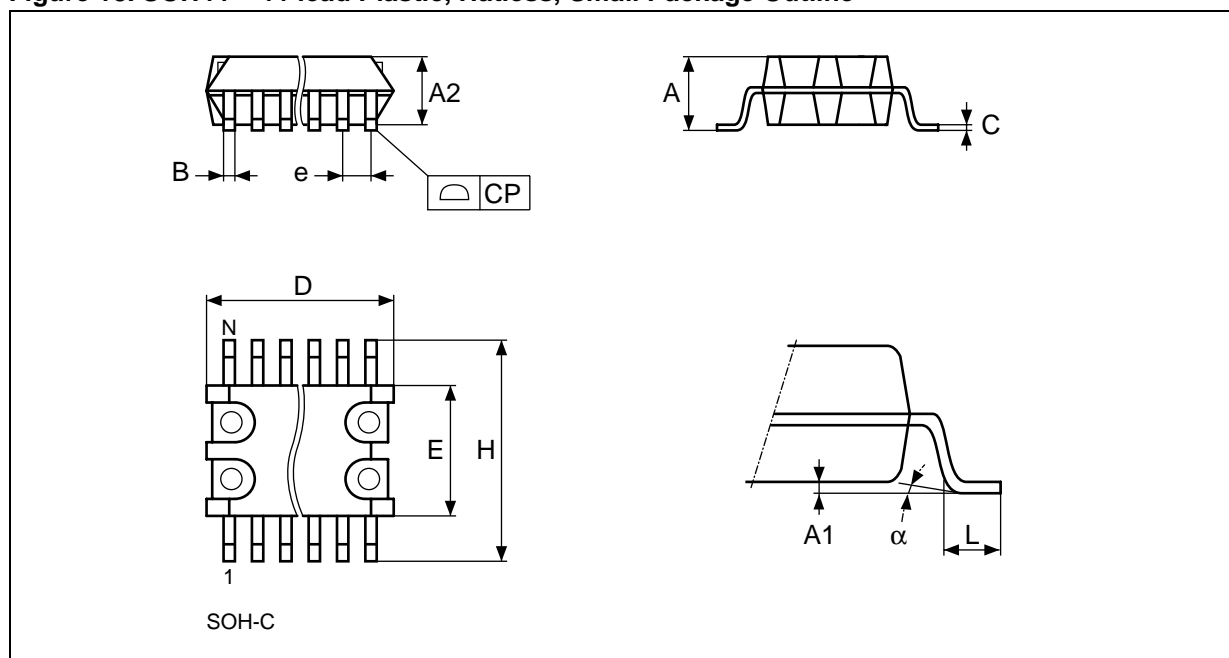


Figure 17. Clock Calibration



PACKAGE MECHANICAL INFORMATION

Figure 18. SOH44 – 44-lead Plastic, Hatless, Small Package Outline

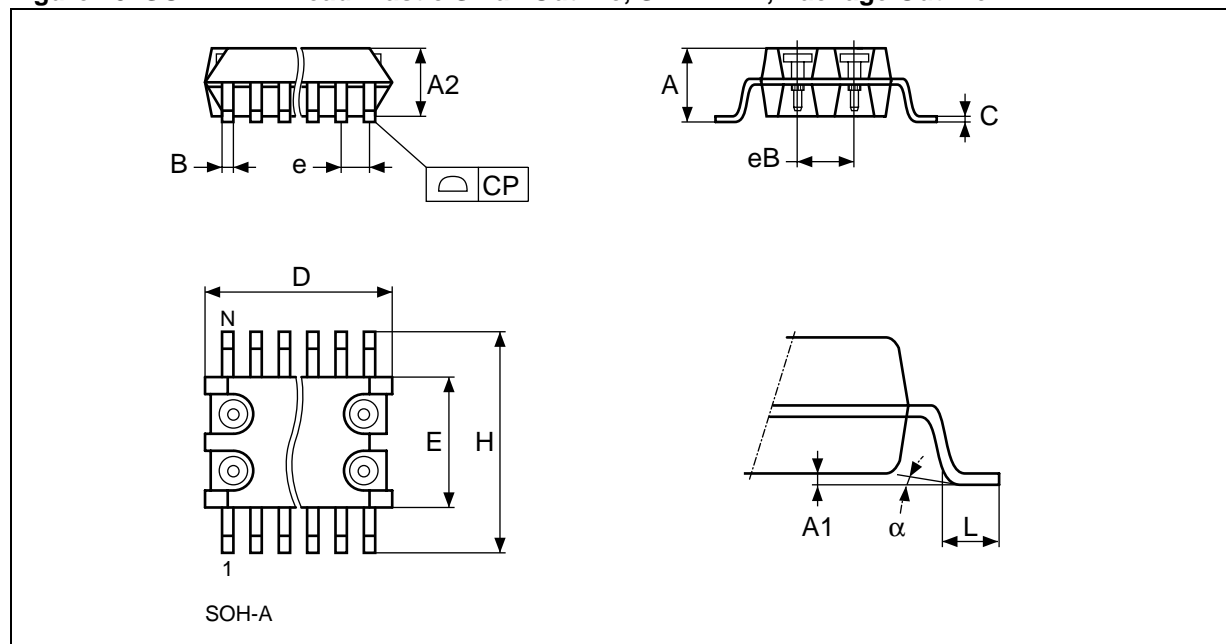


Note: Drawing is not to scale.

Table 11. SOH44 – 44-lead Plastic, Hatless, Small Package Mechanical Data

Symbol	millimeters			inches		
	Typ	Min	Max	Typ	Min	Max
A			3.05		0	0.120
A1		0.05	0.36		0.002	0.014
A2		2.34	2.69		0.092	0.106
B		0.36	0.46		0.014	0.018
C		0.15	0.32		0.006	0.012
D		17.71	18.49		0.697	0.728
E		8.23	8.89		0.324	0.350
e	0.81	–	–	0.032	–	–
H		11.51	12.70		0.453	0.500
L		0.41	1.27		0.016	0.050
α		0°	8°		0°	8°
N	44			44		
CP			0.10			0.004

Figure 19. SOH44 – 44-lead Plastic Small Outline, SNAPHAT, Package Outline

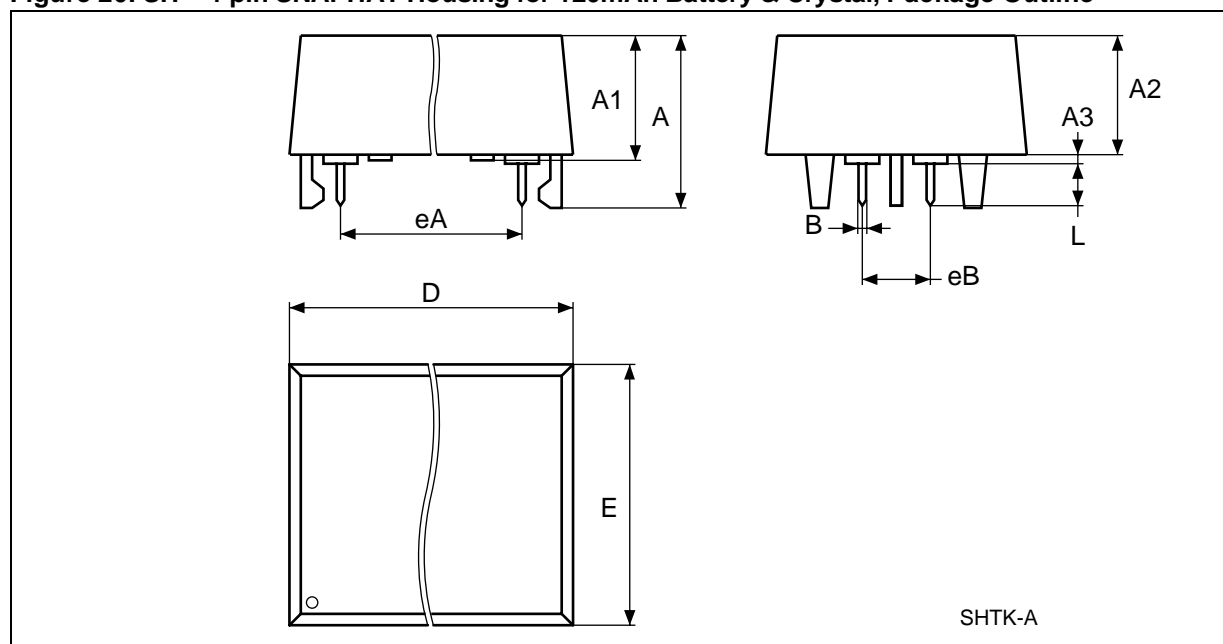


Note: Drawing is not to scale.

Table 12. SOH44 – 44-lead Plastic Small Outline, SNAPHAT, Package Mechanical Data

Symb	mm			inches		
	Typ	Min	Max	Typ	Min	Max
A			3.05			0.120
A1		0.05	0.36		0.002	0.014
A2		2.34	2.69		0.092	0.106
B		0.36	0.46		0.014	0.018
C		0.15	0.32		0.006	0.012
D		17.71	18.49		0.697	0.728
E		8.23	8.89		0.324	0.350
e	0.81	–	–	0.032	–	–
eB		3.20	3.61		0.126	0.142
H		11.51	12.70		0.453	0.500
L		0.41	1.27		0.016	0.050
α		0°	8°		0°	8°
N	44			44		
CP			0.10			0.004

Figure 20. SH – 4-pin SNAPHAT Housing for 120mAh Battery & Crystal, Package Outline



Note: Drawing is not to scale.

Table 13. SH – 4-pin SNAPHAT Housing for 120mAh Battery & Crystal, Package Mechanical Data

Symb	mm			inches		
	Typ	Min	Max	Typ	Min	Max
A			10.54			0.415
A1		8.00	8.51		0.315	.0335
A2		7.24	8.00		0.285	0.315
A3			0.38			0.015
B		0.46	0.56		0.018	0.022
D		21.21	21.84		0.835	0.860
E		17.27	18.03		0.680	.0710
eA		15.55	15.95		0.612	0.628
eB		3.20	3.61		0.126	0.142
L		2.03	2.29		0.080	0.090

PART NUMBERING

Table 14. Ordering Information Scheme

Example:	M41T	256Y	MT	7	TR
Device Type					
M41T					
Supply Voltage and Write Protect Voltage					
256Y = $V_{CC} = 4.5$ to $5.5V$; $V_{PFD} = 4.2$ to $4.5V$					
Package					
MT = 44-lead, Hatless SOIC					
MH ⁽¹⁾ = SOH44					
Temperature Range					
7 = -25 to 70°C					
Shipping Method for SOIC					
blank = Tubes					
TR = Tape & Reel					

Note: 1. The SOIC package (SOH44) requires the battery package (SNAPHAT[®]) which is ordered separately under the part number "M4Txx-BR12SH" in plastic tube or "M4Txx-BR12SHTR" in Tape & Reel form.

Caution: Do not place the SNAPHAT battery package "M4Txx-BR12SH" in conductive foam as it will drain the lithium button-cell battery.

For a list of available options (e.g., Speed, Package) or for further information on any aspect of this device, please contact the ST Sales Office nearest to you.

Table 15. SNAPHAT[®] Battery Table

Part Number	Description	Package
M4T32-BR12SH	Lithium Battery (120mAh) SNAPHAT	SH

REVISION HISTORY**Table 16. Document Revision History**

Date	Rev. #	Revision Details
February 2002	1.0	First Issue
26-Apr-02	1.1	Addition of "Tamper Event Time-Stamp" text
31-May-02	1.2	Add Sleep Mode, 44-pin with SNAPHAT package (Figure 2, 5, 19, 20; Table 1, 2, 14, 15, 12, 13)
03-Jul-02	1.3	Modify Crystal Electrical Characteristics table footnotes (Table 6)
12-Jul-02	1.4	Added programmable Sleep Mode information to document (Figure 3, 4, 5, 6; Table 9, 10)
29-Jul-02	1.5	Add "Hatless" to package description (Figure 1, 18 and Table 14, 11)
20-Dec-02	2.0	I _{CC} Characteristics changed (Table 5); Document promoted to "Datasheet"
04-Jan-03	2.1	Add V _{OL} value (Table 5)
26-Mar-03	2.2	Update test condition (Table 8)

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